thin-plate region that is formed in the fourth substrate of the electro-optical panel.

- 11. An electronic apparatus comprising the electro-optical device according to claim 4.
- 12. A method of manufacturing an input device which includes a first substrate having a coordinate input surface, a second substrate facing the first substrate and an indicator that indicates a position of input by the coordinate input surface.

the method comprising:

bonding the first substrate and the second substrate, each being made of a glass substrate, by sealing materials which are provided in ring shapes on peripheral portions of the first and second substrates; and

forming a thin-plate region having a thinner thickness at the coordinate input surface of the first substrate than the periphery of the coordinate input.

13. The method of manufacturing an input device according to claim 12,

wherein the bonding of the first substrate and the second substrate includes;

bonding a first mother substrate having a plurality of substrate regions, each serving as the first substrate, and a second mother substrate having a plurality of substrate regions, each serving as the second substrate, by the sealing materials formed on the respective substrate regions, and

the forming the thin-plate region at a region which is the coordinate input surface of each of the substrate regions of the first mother substrate.

14. The method of manufacturing an input device according to claim 13, further comprising:

after the forming of the thin-plate region on the first substrate, cutting the bonded first and second mother substrates to separate input devices from each other,

wherein the cutting of the first mother substrate is performed by cutting a region other than the thin-plate region on the first mother substrate.

15. The method of manufacturing an input device according to claim 14,

wherein the first mother substrate and the second mother substrate have the substantially same thickness.

16. A method of manufacturing an electro-optical device which includes an electro-optical panel and an input device arranged on a front surface of the electro-optical panel,

wherein the input device is manufactured by the method according to claim 12.

17. The method of manufacturing an electro-optical device according to claim 16, further comprising:

manufacturing the electro-optical panel,

wherein the manufacturing of the electronic panel includes bonding a third substrate arranged on the front surface and a fourth substrate facing the third substrate by sealing materials which are provided in ring shapes on peripheral portions of the third and fourth substrates, and sealing liquid crystal into a space surrounded by the third substrate, the fourth substrate, and the sealing materials.

18. The method of manufacturing an electro-optical device according to claim 17,

wherein the manufacturing of the electro-optical panel further includes;

forming a thin-plate region of the fourth substrate at a position facing the coordinate input surface of the input device and the position being at a rear surface of the fourth substrate of the electro-optical panel, and

the thin-plate region having a thinner thickness than the periphery of the fourth substrate.

19. The method of manufacturing an electro-optical device according to claim 18,

wherein the bonding the third substrate and the fourth substrate includes;

bonding a third mother substrate having a plurality of substrate regions, each serving as the third substrate, and a fourth mother substrate having a plurality of substrate regions, each serving as the fourth substrate, by the sealing materials formed on the respective substrate regions, and

the forming the thin-plate region at a region which is the coordinate input surface of each of the substrate regions of the fourth mother substrate.

20. The method of manufacturing an electro-optical device according to claim 19, further comprising: after the forming of the thin-plate region on the fourth substrate, cutting the bonded third and fourth mother substrates to separate electro-optical panels from each other,

wherein the cutting the fourth mother substrate is performed by cutting a region other than the thin-plate region on the fourth mother substrate.

21. The method of manufacturing an electro-optical device according to claim 20,

wherein the third mother substrate and the fourth mother substrate have the substantially same thickness.

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